

General Description

The MAX4899E/MAX4899AE analog multiplexers combine the low on-capacitance (C_{ON}) and low on-resistance (R_{ON}) necessary for high-performance switching applications. These devices are designed for USB 2.0 high-speed applications at 480Mbps. The MAX4899E/ MAX4899AE also handle all the requirements for USB low- and full-speed signaling.

The MAX4899E is a dual 3:1 multiplexer whereas the MAX4899AE is a dual 4:1 multiplexer. The MAX4899E/MAX4899AE feature two digital inputs, C_0 and C_1 , to control the analog signal path. Typical applications include switching a USB connector between USB and other operations such as serial communications, audio, and video.

An enable input (\overline{EN}) is provided to disable all channels and place the device into a high-impedance (off) state, as well as reducing power consumption.

The MAX4899E/MAX4899AE operate from a 2.7V to 3.6V power-supply voltage and are protected against +5.5V shorts to COM_A- and COM_A+. In addition, COM_A+ and COM_A- are normally connected to outside circuitry and feature $\pm 15kV$ ESD protection. The MAX4899E/MAX4899AE are available in a 3mm x 3mm, 16-pin TQFN package and operate over the -40°C to $+85^{\circ}C$ temperature range.

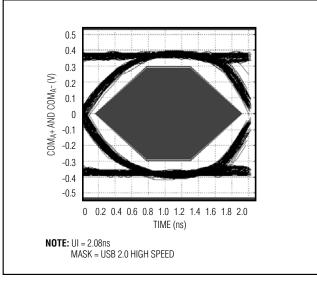
	Applications
Cell Phones	
Digital Still Cameras	
PDAs	
Digital Video Cameras	
MPEG-4 Players	
Portable GPS	
Combination Products	
KVM	

Pin Configurations appear at end of data sheet.

Features

- Single 2.7V to 3.6V Power-Supply Voltage
- Low 4Ω (typ) On-Resistance (RON)
- -3dB Bandwidth: 425MHz
- ♦ Fault Tolerant to Meet Full USB 2.0 Specification
- COM_ Protected to ±15kV ESD Protection per Human Body Model (MIL-STD-883; Method 3015)
- Low Operating Current (200µA), Ultra-Low Quiescent Current (3.0µA max) in Standby Mode
- Low Threshold Eliminates the Need for Translators in 1.8V Low Voltage Systems
- Tiny 16-Pin, 3mm x 3mm, Lead-Free TQFN Package

Eye Diagram



Ordering Information/Selector Guide

PART	PIN-PACKAGE	MUX CONFIGURATION	TOP MARK	PKG CODE	
MAX4899EETE+	16 TQFN-EP*	DUAL 3:1	AEY	T1633-4	
MAX4899AEETE+	16 TQFN-EP*	DUAL 4:1	AEZ	T1633-4	

Note: All devices are specified over the -40°C to +85°C operating temperature range.

+Denotes lead-free package.

*EP = Exposed paddle.

Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

(All Voltages Referenced to GND.)

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Continuous Power Dissipation ($T_A = +70^{\circ}C$)	
16-Pin TQFN (derate 20.8mW/°C above +70)°C) 1667mW
Operating Temperature Range	40°C to +85°C
Storage Temperature Range	65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C

Note 1: Signals exceeding GND are clamped by internal diodes. Limit forward-diode current to maximum current rating.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V + = +2.7V \text{ to } +3.6V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \overline{QP} = \text{low}, \overline{EN} = \text{low}, \text{ unless otherwise noted}$. Typical values are at V + = +3.3V and $T_A = +25^{\circ}C$.) (Note 2)

PARAMETER	SYMBOL	CONDI	TIONS	MIN	ТҮР	МАХ	UNITS
ANALOG SWITCH (COMA_, USB)							
	Ron	V+ = 2.7V, I _{COMA} _ = -10mA, V _{COMA} _ = 0V, 1.5V, <u>QP</u> = low	$T_A = +25^{\circ}C$		4	5	Ω
			$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			6	
		$V_{+} = 2.7V, I_{COMA} = -10mA, V_{COM} = 0V, 1.5V, 2.7V, QP = Iow$	$T_A = +25^{\circ}C$		4	7	
On Desistance			$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			8	
On-Resistance		V+ = 2.7V, I _{COMA} _ = -10mA, V _{COMA} _ = 0V, 1.5V, QP = high	$T_A = +25^{\circ}C$		8	17	
			$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			18	
		V+ = 3.0V, I _{COMA} = -10mA, V _{COMA} = 0V, 1.5V, QP = high	$T_A = +25^{\circ}C$		4	12	
			$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			13	
On-Resistance Match Between	ΔR _{ON}	-10mA, V _{COMA} = 0V,	$T_A = +25^{\circ}C$		0.5	0.8	Ω
Channels			$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			1.0	
On-Resistance Flatness	RFLAT (ON)	V+ = 2.7V, I _{COMA} _ = -10mA, V _{COMA} _ = 0V, 1.5V, 2.7V			0.5	1.1	Ω
Off-Leakage Current	IL(OFF)	$V + = 3.6V, V_{COMA_} = V$	/ _{USB} = 0.3V, 3.3V	-1		+1	μA
On-Leakage Current	IL(ON)	$V + = 3.6V, V_{COMA_} = V_{COMA_}$	/ _{USB} = 0.3V, 3.3V	-1		+1	μΑ
Quiescont Supply Quirront	l+	$V + = 3.6V, C_0 = C_1 =$	$\overline{QP} = low$		250	600	μA
Quiescent Supply Current		0 or V+ $\overline{QP} = high$				3	μΛ
Fault-Protection Trip Threshold	VFP	V + = 3.3V		3.6	3.9	4.2	V
ESD PROTECTION							
COMA+, COMA-		Human Body Model			±15		kV

ELECTRICAL CHARACTERISTICS (continued)

 $(V + = +2.7V \text{ to } +3.6V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \overline{QP} = \text{low}, \overline{EN} = \text{low}, \text{ unless otherwise noted}.$ Typical values are at V + = +3.3V and $T_A = +25^{\circ}C.$ (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN TYP	MAX	UNITS
SWITCH AC PERFORMANCE (N	ote 3)	· · ·			
On-Loss	ONLOSS	$f = 10MHz, 0 < V_{IN} < 1V$, Figure 1	0.5		dB
Crosstalk	V _{CT1} , V _{DCT1}	f = 50MHz, Figure 1	-50		dB
Off-Isolation	VISO	f = 50MHz, Figure 1	-45		dB
Charge-Pump Noise	VQP	$COM_{A_{-}}$, USB_, $R_{L} = R_{S} = 50\Omega$ (Note 4)	100		μV
Bandwidth -3dB	BW	$R_S = R_L = unbalanced 50\Omega$	425		MHz
Off-Capacitance	COFF	$f = 1MHz$, $COM_{A_{-}}$, USB_, Figure 2	10.5		рF
On-Capacitance	CON	$f = 1MHz$, $COM_{A_{-}}$, USB_, Figure 2	15		рF
Propagation Delay	tpD	$R_L = R_S = 50\Omega$, Figure 3	200		ps
Output Skew Same Switch	tsĸ	Skew between opposite transitions in same switch, Figure 3	100		ps
Fault-Protection Response Time	t _{FP}	$V_{COMA_}$ = 0V to 5V to $V_{USB_}$ = 2.5V, R_L = 50 $\Omega,~C_L$ = 10pF, Figure 4	1		μs
Fault-Protection Recovery Time	tFPR	$V_{COMA_}$ = 5V to 3V to $V_{USB_}$ = 1.5V, R_L = 50 $\Omega,~C_L$ = 10pF, Figure 4	1		μs
Charge Injection	Q	$V_{GEN} = 0, C_L = 1000 \text{pF}, Figure 5$	25		рС
Enable Turn-On Time	ton	$V_{USB0+} = V+$, $R_L = 50\Omega$, $C_L = 10$ pF, Figure 6	2.8		μs
Enable Turn-Off Time	tOFF	$V_{USB0+} = V+, R_L = 50\Omega, C_L = 10pF$, Figure 6	6 3		ns
Address Transition Time	ttrans	$V_{USB0+} = V+, R_L = 50\Omega, C_L = 10pF$, Figure 7	97 1.2		μs
Total Harmonic Distortion Plus Noise	THD+N	f = 20Hz to 20kHz, V _{COMA} = 1V _{P-P} , R _L = 600Ω	= 0.02		%
SWITCH LOGIC (QP, EN, C0, C1)					•
Logic-Input Voltage Low	V _{IL} 0.4		0.4	V	
Logic-Input Voltage High	VIH		1.4		V
Input Logic Hysteresis	V _{HYST}		100		mV
Input Leakage Current	Leakage Current I_{LEAK} V+ = 3.6V, C ₀ = 0 or V+, C ₁ = 0 or V+ -1 1		μA		

Note 2: Limits at -40°C are guaranteed by design.

Note 3: Guaranteed by design.

Note 4: Charge-pump noise is specified as a peak-to-peak value.

Typical Operating Characteristics

TIME (ns)

/N/XI/N

 $(V + = 3.3V, \overline{QP} = \overline{EN} = low, T_A = +25^{\circ}C, unless otherwise noted.)$

ON-RESISTANCE vs. VCOM LEAKAGE CURRENT vs. TEMPERATURE **ON-RESISTANCE vs. VCOM** 3.00 5500 3.6 $V_{+} = 3.6V$ 2.98 5000 3.4 4500 2.96 $V_{+} = 2.7V$ TEAKAGE CURRENT (PA) 3500 3500 2500 2500 1500 1000 3.2 2.94 $T_A = +85^{\circ}C$ 3.0 2.92 $V_{+} = 3.3V$ (a) 2.92 Nog 2.90 $R_{ON}(\Omega)$ 4 2.8 $T_A = +25^{\circ}C$ 2.88 COM ON-LEAKAGE 2.6 2.86 V+=3.6V 1000 2.4 COM OFF-LEAKAGE 2.84 $T_A = -40^{\circ}C$ 500 2.2 2.82 0 2.80 -500 2.0 0.6 2.4 3.0 0 1.2 1.8 3.6 0 -40 -15 10 35 60 85 1.1 2.2 3.3 V_{COM} (V) TEMPERATURE (°C) V_{COM} (V) **QUIESCENT SUPPLY CURRENT CHARGE INJECTION vs. VCOM** vs. TEMPERATURE LOGIC THRESHOLD vs. SUPPLY VOLTAGE 300 1.0 30 $C_{L} = 1000 pF$ 280 0.9 QUIESCENT SUPPLY CURRENT (µA) 25 $V_{+} = 3.6V$ 260 V_{IH} 0.8 CHARGE INJECTION (pC) 240 LOGIC THRESHOLD (V) 0.7 20 220 0.6 VIL 200 15 $V_{+} = 3.3V$ 0.5 180 0.4 10 160 0.3 $V_{+} = 2.7V$ 140 0.2 5 120 0.1 100 0 0 1.1 2.2 3.3 -40 -15 35 60 85 0 10 2.7 3.0 3.3 3.6 TEMPERATURE (°C) $V_{COM}(V)$ SUPPLY VOLTAGE (V) TOTAL HARMONIC DISTORTION FREQUENCY RESPONSE **PLUS NOISE vs. FREQUENCY** EYE DIAGRAM 0 0.1 |||||| 0.5 $R_L = 600 \Omega$ -10 **ON-RESPONSE** 0.4 -20 0.3 -30 COMA+ AND COMA- (V) 0.2 -40 LOSS (dB) (%) N+CH. 0.1 OFF-ISOLATION -50 0 -60 -0.1 CROSSTALK -0.2 -70 -0.3 -80 -0.4 -90 -0.5 -100 0.01 1000 1 10 100 100 10 1k 10k 100k 0 0.2 0.4 0.6 0.8 1.0 1.2 1.4 1.6 1.8 2.0

FREQUENCY (Hz)

MAX4899E/MAX4899AE

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FREQUENCY (MHz)

_Pin Description

PIN MAX4899E MAX4899AE		NAME	FUNCTION		
		NAME			
1	1	GND	Ground		
2	2	COM _A +	Analog Switch Common D+ Terminal		
3	3	COM _A -	Analog Switch Common D- Terminal		
4	4	V+	Positive Supply-Voltage Input. Connect V+ to a 2.7V to 3.6V supply voltage. Bypass V+ to GND with a 0.1μ F capacitor placed as close as possible to the device.		
5	5	C ₁	Digital Control Input 1. C_1 and C_0 control the analog signal path as shown in the <i>Functional Diagrams section</i> .		
6	6	C ₀	Digital Control Input 0. C_1 and C_0 control the analog signal path as shown in the <i>Functional Diagrams section</i> .		
7, 8		N.C.	No Connection. Not internally connected.		
—	7	USB3-	Analog Switch 3 D- Terminal		
—	8	USB3+	Analog Switch 3 D+ Terminal		
9	9	USB2-	Analog Switch 2 D- Terminal		
10	10	USB2+	Analog Switch 2 D+ Terminal		
11	11	USB1+	Analog Switch 1 D+ Terminal		
12	12	USB1-	Analog Switch 1 D- Terminal		
13	13	USB0+	Analog Switch 0 D+ Terminal		
14	14	USB0-	Analog Switch 0 D- Terminal		
15	15	Active-Low Enable Input. For normal operation, drive EN low. Drive EN high to place all channels in a high-impedance state. The internal charge pump is turned off when EN is a logic-high.			
16			Active-Low Charge-Pump Enable Input. Drive $\overline{\text{QP}}$ low for normal operation. Drive $\overline{\text{QP}}$ high to disable the charge pump with the switches still active at a reduced analog signal range and higher R _{ON} .		
_		EP	Exposed Paddle. Connect EP to GND.		

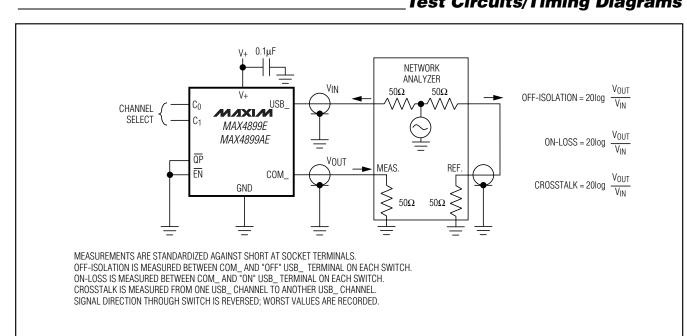


Figure 1. Off-Isolation, On-Loss, and Crosstalk

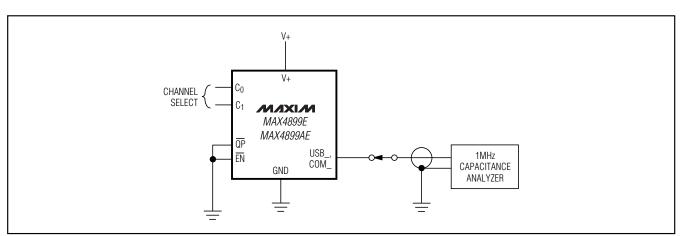


Figure 2. Channel Off-/On-Capacitance

Test Circuits/Timing Diagrams

MAX4899E/MAX4899AE

Test Circuits/Timing Diagrams (continued)

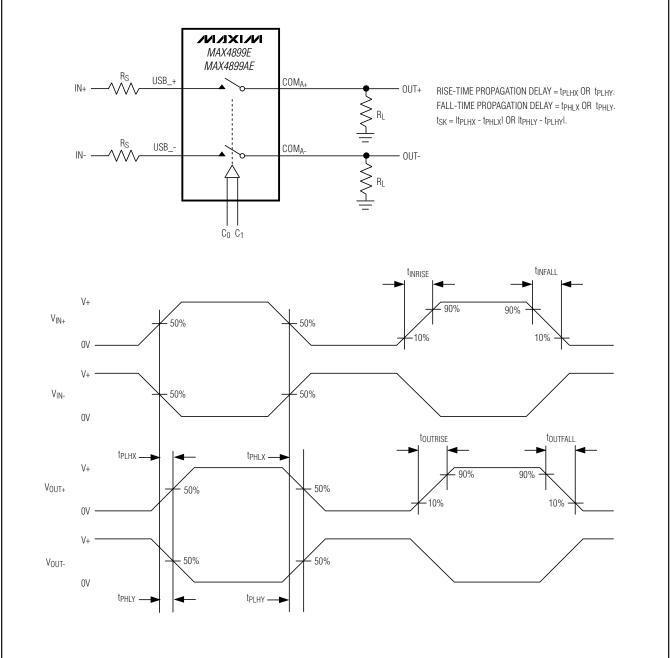


Figure 3. Propagation Delay and Output Skew

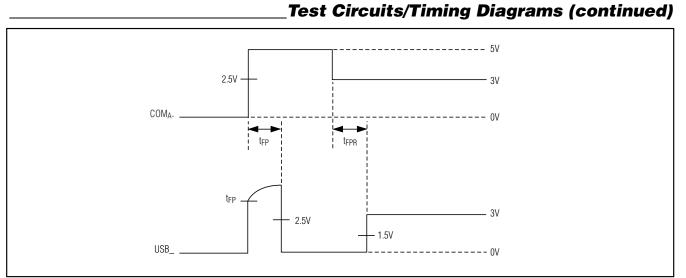


Figure 4. Fault-Protection Response/Recovery Time

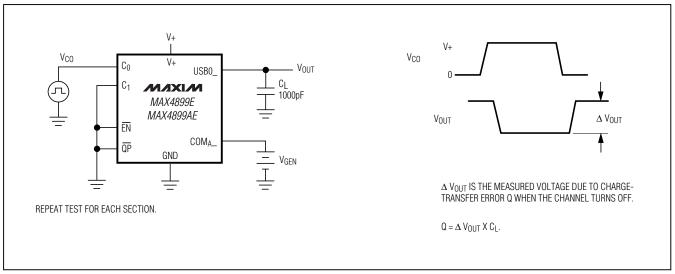
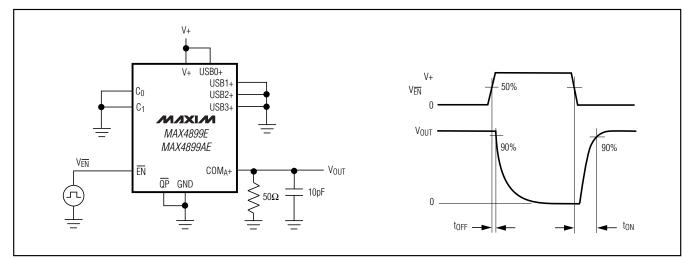


Figure 5. Charge Injection



_Test Circuits/Timing Diagrams (continued)

Figure 6. Enable Switching Times

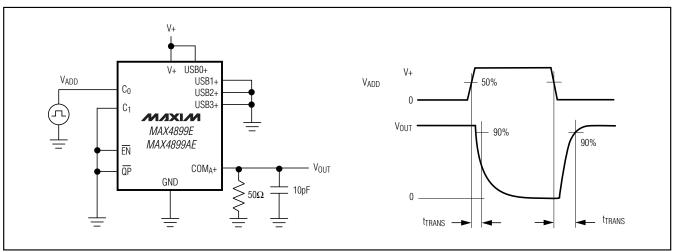


Figure 7. Address Transition Time

MAX4899E/MAX4899AE

_Detailed Description

The MAX4899E/MAX4899AE analog multiplexers combine the low on-capacitance (CON) and low on-resistance (RON) necessary for high-performance switching applications. These devices are designed for USB 2.0 high-speed applications at 480Mbps. The MAX4899E/ MAX4899AE also handle all the requirements for USB low- and full-speed signaling. In the case of USB low/ full speed, these devices can function normally even if the supply voltage is 2.7V, even though the USB signal may be higher than the supply voltage.

The MAX4899E is a dual 3:1 multiplexer, whereas the MAX4899AE is a dual 4:1 multiplexer. The MAX4899E/MAX4899AE feature two digital inputs, C_0 and C_1 , to control the analog signal path. Typical applications include switching a USB connector between USB and other operations such as serial communications, audio, and video.

An enable input (\overline{EN}) is provided to disable all channels and place the device into a high-impedance (off) state, as well as shutting off the charge pump for minimum power consumption. The MAX4899E/MAX4899AE feature an additional charge-pump enable input (\overline{QP}) to disable the charge pump. The switches remain active at a lower analog signal range and higher R_{ON}.

The MAX4899E/MAX4899AE operate from a 2.7V to 3.6V power-supply voltage and are current-limit protected against +5.5V shorts to COMA- and COMA+.

Digital Control Inputs (Co, C1)

The MAX4899E/MAX4899AE provide two digital control inputs (C₀, C₁) to select the analog signal path between the COMA_ and USB_ channels. The truth tables for the MAX4899E/MAX4899AE are shown in the *Functional Diagrams*. Since the MAX4899E only has three USB_ channels, the code C₁:C₀ = 1:1 can be used to place all channels into a high-impedance state. This is particularly useful for eliminating the extra control line to the EN input that is normally used for disabling all channels. Driving C₀ and C₁ rail-to-rail minimizes power consumption.

Enable Input (EN)

The MAX4899E/MAX4899AE feature an enable input (EN) that when driven high places all channels into a high-impedance state, as an all-off feature. The internal charge pump is also disabled when EN is high, thus minimizing the quiescent supply current. For normal operation, drive EN low.

Charge-Pump Enable Input (QP)

The charge-pump input (\overline{QP}) disables and enables the internal charge pump. Drive \overline{QP} high to disable the charge pump and reduce the quiescent supply current.

With the charge pump disabled, the MAX4899E/MAX4899AE still function normally; however, the analog signal range is reduced and the switch on-resistance (R_{ON}) is increased. The analog signal range with the charge pump disabled is 0V to 1.5V. For normal operation, drive \overline{QP} low.

Analog Signal Levels

Signals applied to COM_A+ are routed to the USB_+ terminals, and signals applied to COM_A- are routed to the USB_- terminals. These multiplexers are bidirectional, allowing COM_A_ and USB_ to be configured as either inputs or outputs. The D+ and D- notation in the *Pin Description* table is arbitrary and can be interchanged. For example, USB D+ signals can be applied to COM_Aand are routed to the USB_- terminals. Additionally, these multiplexers can be used for non-USB signals. COM_A+ and COM_A- are normally connected to outside circuitry and are ±15kV ESD protected.

The MAX4899E is a dual 3:1 multiplexer, allowing COM_A+ to be routed to one of three USB_+ channels, and COM_A- to be routed to one of three USB_- channels. The MAX4899AE is a dual 4:1 multiplexer, allowing COM_A+ to be routed to one of four USB_+ channels, and COM_A- to be routed to one of four USB_- channels.

Overvoltage Fault Protection

The MAX4899E/MAX4899AE feature +5.5V fault protection to COM_A+ and COM_A-. When a fault occurs between 4.5V to 5.5V, the switch automatically goes into a current-limiting mode that limits current to less than 2mA. Fault protection prevents these switches and downstream devices from being damaged due to shorts to the USB bus voltage rail.

Applications Information

USB Switching

The MAX4899E/MAX4899AE analog multiplexers are fully compliant with the USB 2.0 specification. The low on-resistance and low on-capacitance of these multiplexers make them ideal for high-performance switching applications. The MAX4899E/MAX4899AE are ideal for routing USB data lines and for applications that require switching between different data types (see Figure 8).

Board Layout

High-speed switches require proper layout and design procedures for optimum performance. Keep designcontrolled impedance PC board traces as short as possible. Ensure that bypass capacitors are placed as close to the device as possible and use large ground planes where possible.

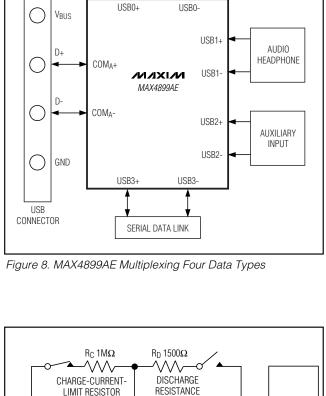




As with all Maxim devices, ESD-protection structures are incorporated on all pins to protect against electrostatic discharges encountered during handling and assembly. The COM_A+ and COM_A- lines have extra protection against static electricity. Maxim's engineers have developed state-of-the-art structures to protect these pins against ESD of ± 15 kV without damage. The ESD structures withstand high ESD in all states: normal operation, tri-state output mode, and powered down. After an ESD event, Maxim's E-versions keep working without latchup, whereas competing products can latch and must be powered down to remove latch-up.

Human Body Model

The MAX4899E/MAX4899AE COMA+ and COMA- pins are characterized for ± 15 kV ESD protection using the Human Body Model (MIL-STD-883, Method 3015). Figure 9a shows the Human Body Model and Figure 9b shows the current waveform it generates when discharged into a low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the device through a 1.5k Ω resistor.



STORAGE

CAPACITOR

LISB

TRANSCEIVER

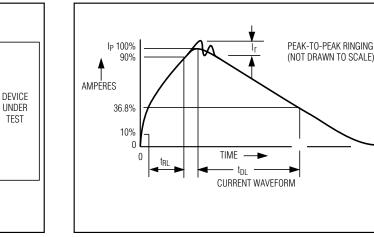


Figure 9b. Human Body Model Current Waveform

Chip Information

PROCESS: BICMOS

HIGH-

VOLTAGE

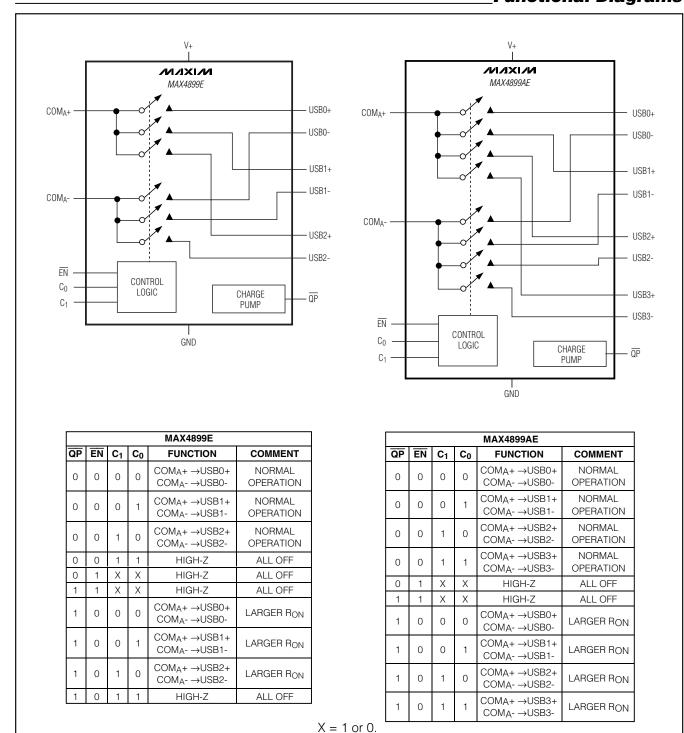
DC

SOURCE

C<u>s</u>

100nĒ

Figure 9a. Human Body ESD Test Model



_Functional Diagrams

MAX4899E/MAX4899AE

Pin Configurations

